

Electronic Patent Application Fee Transmittal

Application Number:	10717122
Filing Date:	19-Nov-2003
Title of Invention:	DIELECTRIC BARRIER LAYER FOR A COPPER METALLIZATION LAYER HAVING A VARYING SILICON CONCENTRATION ALONG ITS THICKNESS
First Named Inventor/Applicant Name:	Larry Zhao
Filer:	J. Mike Amerson/Mary Paul
Attorney Docket Number:	2000.106900

Filed as Large Entity

Utility Filing Fees

Description	Fee Code	Quantity	Amount	Sub-Total in USD(\$)
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Basic Filing:

Pages:

Claims:

Miscellaneous-Filing:

Petition:

Patent-Appeals-and-Interference:

Post-Allowance-and-Post-Issuance:

Utility Appl issue fee	1501	1	1440	1440
Publ. Fee- early, voluntary, or normal	1504	1	300	300

Description	Fee Code	Quantity	Amount	Sub-Total in USD(\$)
Extension-of-Time:				
Miscellaneous:				
Total in USD (\$)				1740